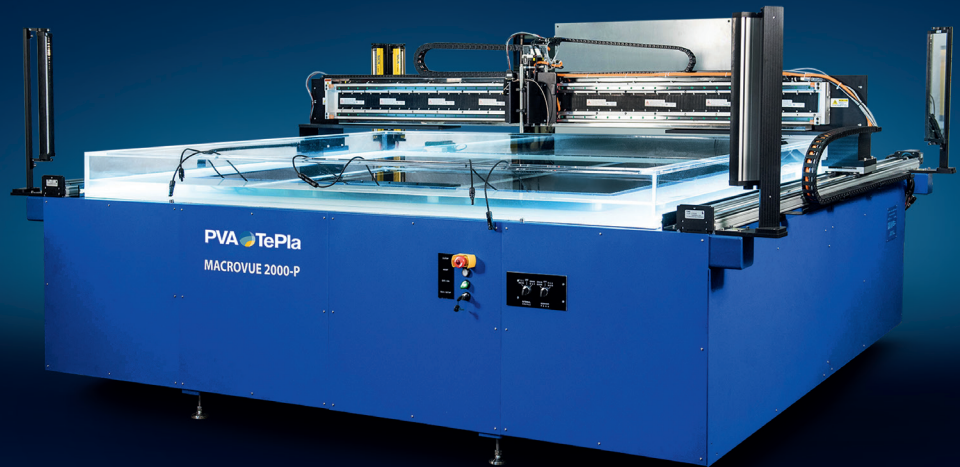


MACROVUE-P

PRODUCT OVERVIEW

LARGE FORMAT ULTRASONIC INSPECTION PLATFORM



SCANNING ACOUSTIC MICROSCOPY

MACROVUE-P

LARGE-SCALE BUT PRECISE.

Our large-format ultrasonic NDT system, purpose-built for industrial-scale inspection challenges. Using next-generation acoustic microscopy, it reliably detects defects such as voids, delaminations, cracks, and bonding failures – non-destructive, with exceptional resolution and repeatability.

FEATURES AT A GLANCE



Largest scan field in the Vue series

600 × 600 mm up to 2,500 × 1,500 mm – inspects panels, composites, and large-format assemblies



Full frequency range: 1–230 MHz

Acoustic imaging preserves sample integrity – ideal for production-critical and high-value components



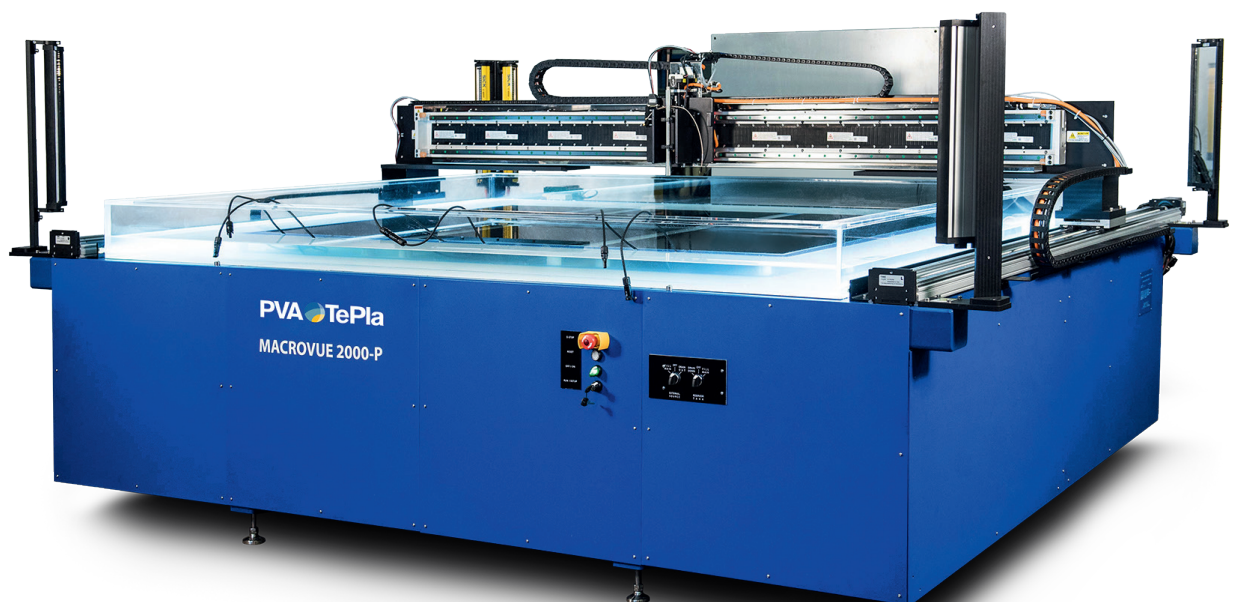
ODIS Software – powered by intelligence

Advanced data-driven analysis: Go/No-Go classification, void quantification, cluster analysis, and multi-zone inspection (SALI). Scalable from R&D to full production environments



Multiple scanning modes

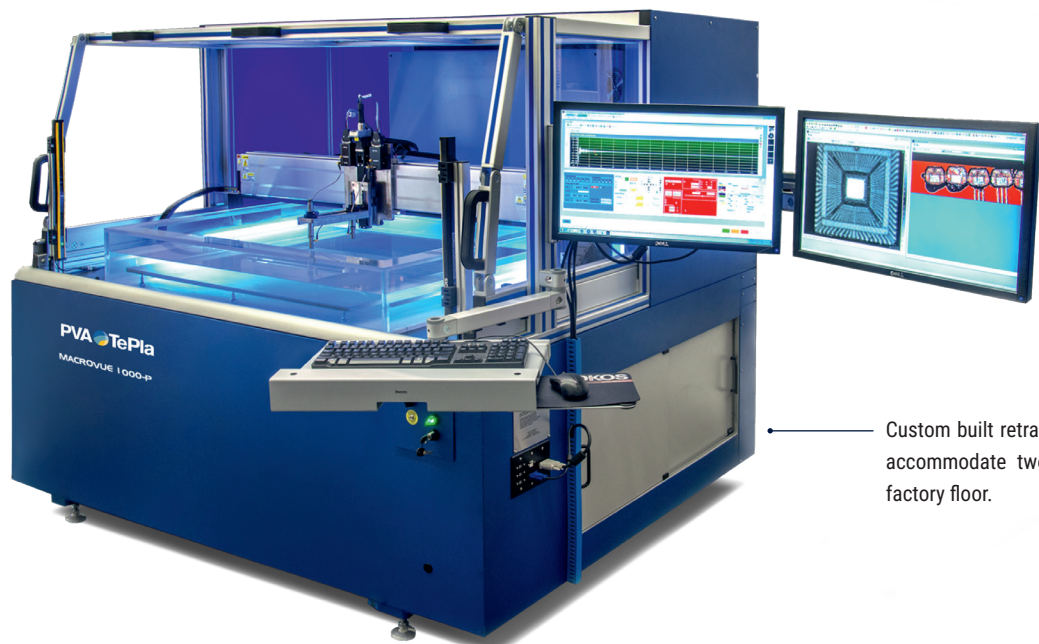
Pulse-Echo, Through-Transmission, A-Scan, B-Scan, C-Scan, TOF (Time of Flight), THK (Thickness) – all in one inspection



TECHNICAL PARAMETERS

Every detail matters. The MACROVUE-P is engineered for large-scale precision inspection — trusted across energy, aerospace & defense, automotive, semiconductor, and medical industries.

SPECIFICATIONS	
Scan Field	600 × 600 mm to 2,500 × 1,500 mm
Transducer Frequency Range	1 MHz to 230 MHz
Pulser-Receiver	1 to 500 MHz
ADC / Digitizer	8 bit, 1 to 12 GHz
Power Supply	120/240 V AC, 20 Amps, 1 PH
Weight & Dimensions	based on customer requirements
Water	Type 2 de-ionized
Tank Options	Acrylic or Steel Tank
Enclosure Option	Retractable Enclosure (optional)
Operating System	Windows 11 Pro O/S
Safety	Safety Light Curtains
SCANNING MODES	
Pulse-Echo	Single-transducer reflection imaging
Through-Transmission	Two-transducer transmission imaging
A-Scan Waveforms	Time-domain signal display
B-Scan	Cross-section images
C-Scan	Planar top-down images
TOF	Time of Flight mapping
THK	Thickness mapping
Measurements	Time Domain Frequency Domain Max. Peak Amplitude Positive and Negative Peak Amplitude Time of Flight to Peaks & Edges End-User Signal Processing
SOFTWARE ODIS INSPECTION & ANALYSIS FEATURES	
Inspection	Multi Zone Inspection (SALI), C-Scans, B-Scans, A-Scan
Detection	Defect Detection, Void Analysis, Cluster Analysis
Measurement	Peak Amplitude, Time of Flight, Thickness Measurement
Classification	Go/No-Go Classification, Quantification, Histogram
User Modes	Advanced · Engineer · Operator



Custom built retractable enclosure to accommodate two story mezzanine factory floor.



Serving Solar Panel industry.

Deep steel tank for inspection of diffusion bonded parts.



Special fixturing for battery cell inspection.

Flexible configuration for specialist labs with a wide range of samples.





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